9999.00 EUR
incl. 19% VAT, plus shipping

- NVidia Jetson AGX !
- 64 GB !
- D317AO-002 !

AVerMedia Carrier Board D317AO support NVIDIA® Jetson AGX Orin , which brings next-level AI performance and power-efficient capability for all autonomous machines. This optional SoM makes advanced analytics possible while providing the ability to handle a host of other embedded IoT applications.

D317AO includes a 120-pin high-speed connector for connecting MIPI SerDes cameras, which can fulfill the demand for AMRs. In addition, a sufficient Ethernet bandwidth with 10G is excellent for applying smart security, enabling dozens of IP cameras to stream simultaneously. The connector for the 10GigE Vision Camera is also great for smart inspection. Lastly, with its compact size, D315 5G furnishes a PCIe slot for multi-function expansion and excellent compatibility with 5G and Wi-Fi 6.

- Embedded NVIDIA® Jetson AGX Orin module
- 1x GbE RJ-45
- 2x NVMe M.2 Key M 2280 (1x only support S1 Type Top side component SSD)
- 1x M.2 Key E 2230 for WIFI 6
- 1x HDMI 2.0 (3840x2160 at 60Hz)
- 1x 120pin for GMSL camera board
- 1x USB 3.2 Type-C for BSP install
- Optional: 2x 10G RJ-45 (via daughter board)
- Optional: 8x PoE (via daughter board)
- Optional: 1x M.2 Key B for 5G connection (via daughter board)
- Operating temperature: -40 to 85°C (carrier board) (TBD)
- Dimension: W: 92mm x L: 107mm (TBD)

NVIDIA GPU SoC Module Compatibility	NVIDIA® Jetson AGX Orin module (64GB)

Networking	1x GbE RJ-45 1 x M.2 key E 2230 for wifi 6 Optional 2x 10G RJ-45 (via daughter board) (TBD) Optional 8x PoE (via daughter board) (TBD) Optional 1x M.2 Key B for 5G connection (via 5G PoE/5G■USB/5G daughter board) (TBD)
Display Output	1 x HDMI output 3840 x 2160 at 60Hz
Temperature	Operating temperature: -40 to 85°C (carrier board), -20 to 70°C (with fan) (TBD) Storage temperature -40°C ~ 85°C (TBD) Relative humidity 40 °C @ 95%, Non-Condensing
Camera Inputs	1x 120pin for GMSL camera board
USB	1x USB 3.2 Type-C for BSP install (supports OTG mode,when using with PoE/5G daughter board or USB/5G daughter board ,the USB 3.2 OTG port becomes USB 2.0) 1x USB 3.2 Type-C (host mode only) Optional 8x USB3.2 Type-A (via daughter board) (TBD)
Storage	2x NVMe M.2 Key M 2280 (1x only support S1 Type Top side component SSD)
TPM (Trusted Platform Module)	Built in Infineon SLB 9672 TPM Chip
Expansion Header	• 30pin header: 1xUART, 1xI2C, 3xGPIO,1xSPI, 2xCAN BUS, 1xI2S, 5V(Maximum 0.7A), 3.3V(Maximum 0.7A) •12pin header: 1x12V(Maximum 0.7A), 1x5V(Maximum 1A), 1x3.3V(Maximum 1A) power Output, 1xUSB 2.0, 1xDMIC •16pin wafer for OOB or External Button: -OOB: 1xUART, 1xDebug UART, 1xPower button, 1xReset button, 1x Power detect (via out-of-band management module) -External Buttons: 1xPower Button, 1xReset button, 1xRecovery button, 1xPWR_LED (via external button cable) •40pin coaxial connector for 10G expansion •40pin coaxial connector for PCIe expansion
GPS	Optional Dual-RTK GNSS support (via daughter board)
Sensor	Temperature sensor for PCB top/bot Temperature measure
Power requirement	Mini-Fit 4pin compatible ,12V +/- 5% DC Input
Thermal Solution	Fan solution (12V fan wafer)
RTC Battery	Support RTC Battery and Battery Life Monitoring by MCU
PCB/Electronics Mechanical Info	W: 92mm x L: 107mm (TBD) •Weight: 1kg (TBD)
Certifications	CE, FCC, VCCI,KC